



ASE Innovates at SemiTech Taipei 2006

ASE showcases its high-end packaging for Optoelectronics and Graphic Process Unit packages

Taipei, Taiwan, May, 3rd, 2006 – Advanced Semiconductor Engineering Incorporated (ASE, TAIEX: 2311, NYSE: ASX), the world's largest semiconductor packaging and test company, announced today that it will participate in the premiere SemiTech Taipei on May 3-6, 2006 at the Taipei World Trade Center. ASE will display an array of advanced packages including a Graphic Processor Unit, and Optoelectronics packages comprising two megapixel Auto Focus CCM, as well as MEMS microdisplays.

During the exhibition, ASE will demonstrate high resolution images generated by the two megapixel Auto Focus CCM, featuring a specialized integrated circuit (IC) packaged by ASE for notebook and digital mobile phone applications. Visitors can also view high-definition images emitting from a projector embedded with MEMS Microdisplay technology. In addition, ASE will showcase vivid 3D effects from a leading-edge game console, comprising 90nm wafer technology packaged within the Graphic Processor Unit, and capable of high performance and high definition visuals. ASE will also present its substrate capabilities, including BGA and Flip Chip substrates, as well as reveal current and future trends for the advanced packages including SiP, Bumping, Flip Chip, Optoelectronics and WLCSP.

"2006 is a milestone year as it marks the 30th year of the semiconductor industry in Taiwan, as well as the 10th anniversary of TSIA. As the number two semiconductor player in Taiwan, ASE is pleased to join our industry colleagues as together we showcase the technology innovation and breakthrough that keeps our industry vibrant and progressive," said Dr. Tien Wu, COO of ASE. "ASE's advanced packaging and test capabilities are integral to the most sophisticated electronic products on the market today. As a company, we place huge focus on R&D in order to keep our customers profitable and to provide complete turnkey services, which meet customer demands for emerging applications and trends in the highly-competitive 4C market."

ASE will demonstrate its advanced packaging and complete turnkey solutions at booth #329 -332, located in Section A of the Taipei World Trade Center. For further event information, please visit <http://semitech.tca.org.tw/cpage/index.php>

About ASE Group

The ASE Group is the world's largest provider of independent semiconductor manufacturing services in assembly and test. As a global leader geared towards meeting the industry's ever growing needs for faster, smaller and higher performance chips, the Group develops and offers a wide portfolio of technology and solutions including IC test program design, front-end engineering test, wafer probe, wafer bump, substrate design and supply, wafer level package, flip chip, system-in-package, final test and electronic manufacturing services through Universal Scientific Industrial Co Ltd, a member of the ASE Group. The Group generated sales revenues of \$2.62 billion in 2005 and employs over 30,000 people worldwide. For more information about the ASE Group, visit www.aseglobal.com.

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